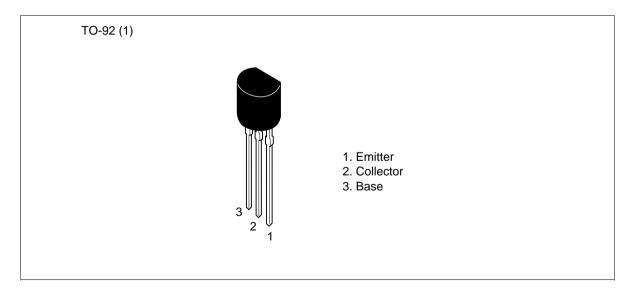
Silicon PNP Epitaxial

# HITACHI

#### Application

- Low frequency low noise amplifier
- Complementary pair with 2SC458 (LG) and 2SC2310

#### Outline





# **Absolute Maximum Ratings** (Ta = $25^{\circ}$ C)

Item	Symbol	2SA1031	2SA1032	Unit
Collector to base voltage	V <sub>CBO</sub>	-30	-55	V
Collector to emitter voltage	V <sub>CEO</sub>	-30	-50	V
Emitter to base voltage	V <sub>EBO</sub>	-5	-5	V
Collector current	Ι <sub>c</sub>	-100	-100	mA
Emitter current	Ι <sub>Ε</sub>	100	100	mA
Collector power dissipation	Pc	300	300	mW
Junction temperature	Tj	150	150	°C
Storage temperature	Tstg	-55 to +150	-55 to +150	°C

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# **Electrical Characteristics** (Ta = 25°C)

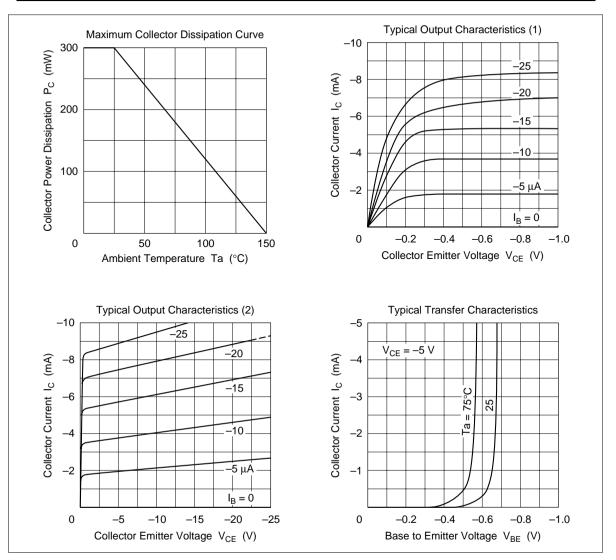
2SA1032

100 to 200

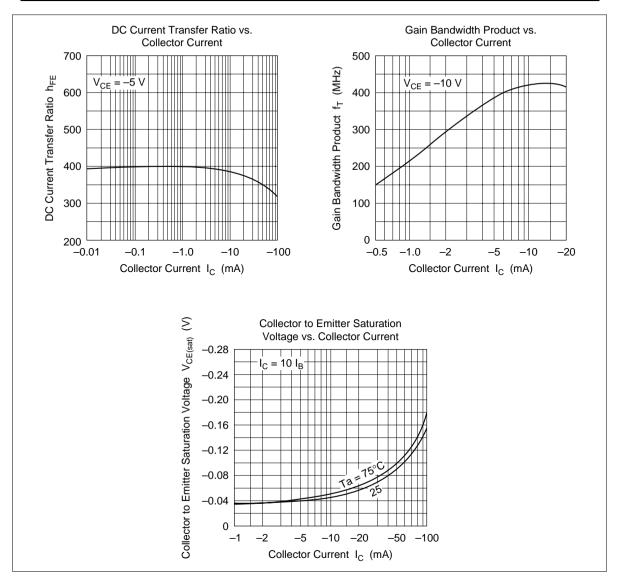
160 to 320

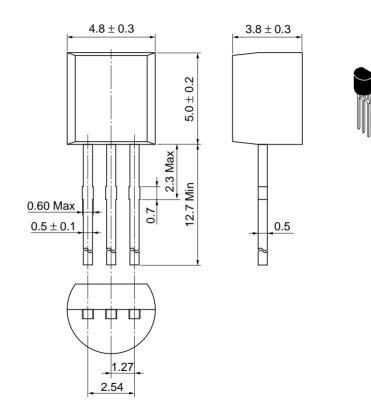
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		2SA1	031		2SA1	2SA1032			
Item	Symbol	Min	Тур	Мах	Min	Тур	Max	Unit	Test conditions
Collector to base breakdown voltage	$V_{\rm (BR)CBO}$	-30	_	—	-55	—	_	V	$I_{c} = -10 \ \mu A, \ I_{E} = 0$
Collector to emitter breakdown voltage	$V_{\rm (BR)CEO}$	-30	—	—	-50	—	—	V	$I_c = -1 \text{ mA}, \text{ R}_{BE} = \infty$
Emitter to base breakdown voltage	$V_{\rm (BR)EBO}$	-5	—	_	-5	_	_	V	$I_{\rm E} = -10 \ \mu A, \ I_{\rm C} = 0$
Collector cutoff current	I <sub>CBO</sub>		—	-0.5	_		-0.5	μΑ	$V_{\rm CB} = -18 \text{ V}, I_{\rm E} = 0$
Emitter cutoff current	I <sub>EBO</sub>		_	-0.5		_	-0.5	μΑ	$V_{EB} = -2 V, I_{C} = 0$
DC current trnsfer ratio	$h_{FE}^{*1}$	100	_	500	100	—	320		$V_{ce} = -12 V,$ $I_c = -2 mA$
Base to emitter voltage	$V_{BE}$	—	—	-0.8	_		-0.8	V	$V_{ce} = -12 V,$ $I_{c} = -2 mA$
Collector to emitter saturation voltage	$V_{\text{CE(sat)}}$	_	—	-0.2	—	—	-0.2	V	$I_{c} = -10 \text{ mA},$ $I_{B} = -1 \text{ mA}$
Gain bandwidth product	f <sub>T</sub>	200	280	—	200	280		MHz	$V_{ce} = -12 V,$ $I_{c} = -2 mA$
Collector output capacitance	Cob	—	3.3	4.0	_	3.3	4.0	pF	$V_{CB} = -10 \text{ V}, \text{ I}_{E} = 0,$ f = 1 MHz
Noise figure	NF	_	_	5	_	_	5	dB	$V_{cE} = -6 V,$ $I_c = -0.1 mA,$ $R_g = 500 \Omega,$ f = 120 Hz
Note: 1. The 2SA103	1 and 2SA	1032 a	re grou	ped by	h <sub>FE</sub> as	follows.			
В	С		D		_				
2SA1031 100 to 20	0 160 t	o 320	250 1	to 500					



#### **HITACHI**





Hitachi Code	TO-92 (1)
JEDEC	Conforms
EIAJ	Conforms
Weight (reference value)	0.25 g

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